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Details	
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Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
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Number of I/O	44
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	224 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 43x10b; D/A 1x5b
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Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf15386-i-pt

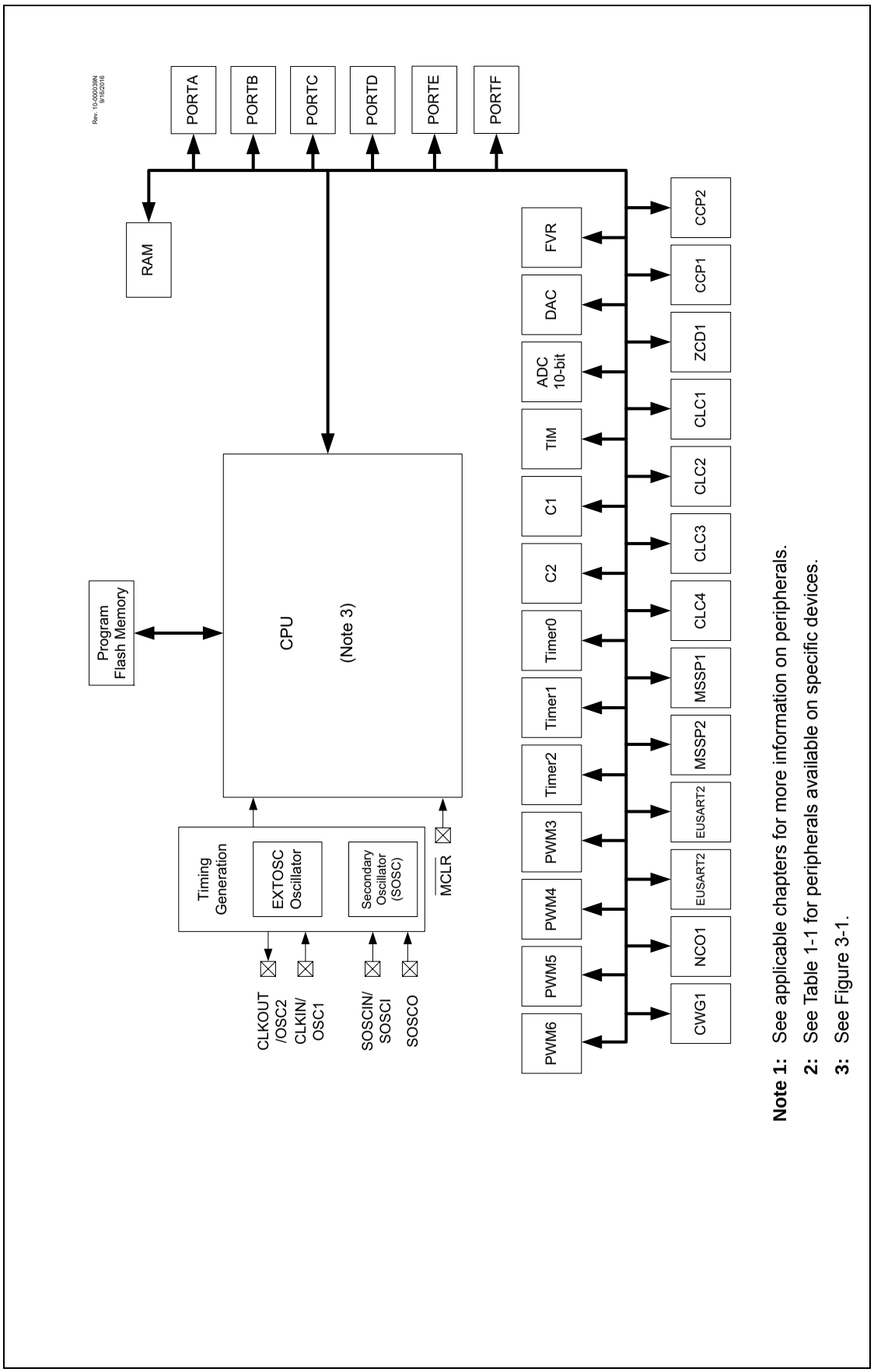


FIGURE 1-3: PIC16(L)F15385/86 BLOCK DIAGRAM

Note 1: See applicable chapters for more information on peripherals.

2: See Table 1-1 for peripherals available on specific devices.

3: See Figure 3-1.

TABLE 1-2: PIC16(L)F15356 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RB3/ANB3/C1IN2-/C2IN2-/IOCB3	RB3	TTL/ST	CMOS/OD	General purpose I/O.
	ANB3	AN	—	ADC Channel B3 input.
	C1IN2-	AN	—	Comparator 1 negative input.
	C2IN2-	AN	—	Comparator 2 negative input.
	IOCB3	TTL/ST	—	Interrupt-on-change input.
RB4/ANB4/ADACT(1)/IOCB4	RB4	TTL/ST	CMOS/OD	General purpose I/O.
	ANB4	AN	—	ADC Channel B4 input.
	ADACT(1)	TTL/ST	—	ADC Auto-Conversion Trigger input.
	IOCB4	TTL/ST	—	Interrupt-on-change input.
RB5/ANB5/T1G(1)/IOCB5	RB5	TTL/ST	CMOS/OD	General purpose I/O.
	ANB5	AN	—	ADC Channel B5 input.
	T1G(1)	ST	—	Timer1 Gate input.
	IOCB5	TTL/ST	—	Interrupt-on-change input.
RB6/ANB6/CLCIN2(1)/IOCB6/TX2/CK2(3)/ICSPCLK	RB6	TTL/ST	CMOS/OD	General purpose I/O.
	ANB6	AN	—	ADC Channel B6 input.
	CLCIN2(1)	TTL/ST	—	Configurable Logic Cell source input.
	IOCB6	TTL/ST	—	Interrupt-on-change input.
	TX2	—	CMOS	EUSART2 asynchronous.
	CK2(3)	TTL/ST	CMOS/OD	EUSART2 synchronous mode clock input/output.
	ICSPCLK	ST	—	In-Circuit Serial Programming™ and debugging clock input.
RB7/ANB7/RX2/DT2/CLCIN3(1)/IOCB7/DAC1OUT2/ICSPDAT	RB7	TTL/ST	CMOS/OD	General purpose I/O.
	ANB7	AN	—	ADC Channel B7 input.
	CLCIN3(1)	TTL/ST	—	Configurable Logic Cell source input.
	IOCB7	TTL/ST	—	Interrupt-on-change input.
	RX2(1)	TTL/ST	—	EUSART2 Asynchronous mode receiver data input.
	DT2(3)	TTL/ST	CMOS/OD	EUSART2 Synchronous mode data input/output.
	DAC1OUT2	—	AN	Digital-to-Analog Converter output.
	ICSPDAT	ST	CMOS	In-Circuit Serial Programming™ and debugging data input/output.
RC0/ANC0/T1CKI(1)/IOCC0/SOSCO	RC0	TTL/ST	CMOS/OD	General purpose I/O.
	ANC0	AN	—	ADC Channel C0 input.
	T1CKI(1)	TTL/ST	—	Timer1 external digital clock input.
	IOCC0	TTL/ST	—	Interrupt-on-change input.
	SOSCO	—	AN	32.768 kHz secondary oscillator crystal driver output.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C
HV = High Voltage; XTAL = Crystal levels

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to Table 15-4 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 15-3.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMBus input buffer thresholds.

TABLE 1-2: PIC16(L)F15356 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
OUT(2)	C1OUT	—	CMOS/OD	Comparator 1 output.
	C2OUT	—	CMOS/OD	Comparator 2 output.
	SDO1	—	CMOS/OD	MSSP1 SPI serial data output.
	SCK1	—	CMOS/OD	MSSP1 SPI serial clock output.
	SDO2	—	CMOS/OD	MSSP2 SPI serial data output.
	SCK2	—	CMOS/OD	MSSP2 SPI serial clock output.
	TX1	—	CMOS/OD	EUSART1 Asynchronous mode transmitter data output.
	CK1(3)	—	CMOS/OD	EUSART1 Synchronous mode clock output.
	TX2	—	CMOS/OD	EUSART2 Asynchronous mode transmitter data output.
	CK2(3)	—	CMOS/OD	EUSART2 Synchronous mode clock output.
	DT(3)	—	CMOS/OD	EUSART Synchronous mode data output.
	TMR0	—	CMOS/OD	Timer0 output.
	CCP1	—	CMOS/OD	CCP2 output (compare/PWM functions).
	CCP2	—	CMOS/OD	CCP2 output (compare/PWM functions).
	PWM3OUT	—	CMOS/OD	PWM3 output.
	PWM4OUT	—	CMOS/OD	PWM4 output.
	PWM5OUT	—	CMOS/OD	PWM5 output.
	PWM6OUT	—	CMOS/OD	PWM6 output.
	CWG1A	—	CMOS/OD	Complementary Waveform Generator 1 output A.
	CWG1B	—	CMOS/OD	Complementary Waveform Generator 1 output B.
	CWG1C	—	CMOS/OD	Complementary Waveform Generator 1 output C.
	CWG1D	—	CMOS/OD	Complementary Waveform Generator 1 output D.
	CLC1OUT	—	CMOS/OD	Configurable Logic Cell 1 output.
	CLC2OUT	—	CMOS/OD	Configurable Logic Cell 2 output.
	CLC3OUT	—	CMOS/OD	Configurable Logic Cell 3 output.
	CLC4OUT	—	CMOS/OD	Configurable Logic Cell 4 output.
	NCO1OUT	—	CMOS/OD	Numerically Controller Oscillator output.
	CLKR	—	CMOS/OD	Clock Reference module output.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C
HV = High Voltage; XTAL = Crystal levels

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to Table 15-4 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 15-3.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMBus input buffer thresholds.

TABLE 1-3: PIC16(L)F15375/76 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/ANA0/C1IN0-/C2IN0-/CLCIN0(1)/IOCA0	RA0	TTL/ST	CMOS/OD	General purpose I/O.
	ANA0	AN	—	ADC Channel A0 input.
	C1IN0-	AN	—	Comparator negative input.
	C2IN0-	AN	—	Comparator negative input.
	CLCIN0(1)	TTL/ST	—	Configurable Logic Cell source input.
	IOCA0	TTL/ST	—	Interrupt-on-change input.
RA1/ANA1/C1IN1-/C2IN1-/CLCIN1(1)/IOCA1	RA1	TTL/ST	CMOS/OD	General purpose I/O.
	ANA1	AN	—	ADC Channel A1 input.
	C1IN1-	AN	—	Comparator negative input.
	C2IN1-	AN	—	Comparator negative input.
	CLCIN1(1)	TTL/ST	—	Configurable Logic Cell source input.
	IOCA1	TTL/ST	—	Interrupt-on-change input.
RA2/ANA2/C1IN0+/C2IN0+/DAC1OUT1/IOCA2	RA2	TTL/ST	CMOS/OD	General purpose I/O.
	ANA2	AN	—	ADC Channel A2 input.
	C1IN0+	AN	—	Comparator positive input.
	C2IN0+	AN	—	Comparator positive input.
	DAC1OUT1	—	AN	Digital-to-Analog Converter output.
	IOCA2	TTL/ST	—	Interrupt-on-change input.
RA3/ANA3/C1IN1+/VREF+/DACREF+/IOCA3	RA3	TTL/ST	CMOS/OD	General purpose I/O.
	ANA3	AN	—	ADC Channel A3 input.
	C1IN1+	AN	—	Comparator positive input.
	VREF+	AN	—	External ADC and/or DAC positive reference input.
	IOCA3	TTL/ST	—	Interrupt-on-change input.
RA4/ANA4/T0CKI(1)/IOCA4	RA4	TTL/ST	CMOS/OD	General purpose I/O.
	ANA4	AN	—	ADC Channel A4 input.
	T0CKI(1)	TTL/ST	—	Timer0 clock input.
	IOCA4	TTL/ST	—	Interrupt-on-change input.
RA5/ANA5/$\overline{SS1}$(1)/T1G(1)/IOCA5	RA5	TTL/ST	CMOS/OD	General purpose I/O.
	ANA5	AN	—	ADC Channel A5 input.
	$\overline{SS1}$(1)	TTL/ST	—	MSSP1 SPI slave select input.
	T1G(1)	TTL/ST	—	Timer1 gate input.
	IOCA5	TTL/ST	—	Interrupt-on-change input.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C
HV = High Voltage; XTAL = Crystal levels

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to Table 15-4 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 15-5, Table 15-6 and Table 15-6.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMBus input buffer thresholds.

TABLE 1-4: PIC16(L)F15385/86 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RD1/AND1/SDA2(1)/SDI2(1,4)	RD1	TTL/ST	CMOS/OD	General purpose I/O.
	AND1	AN	—	ADC Channel D0 input.
	SDA2(1)	I^2C	OD	MSSP2 I^2C serial data input/output.
	SDI2(1,4)	TTL/ST	—	MSSP2 SPI serial data input (default input location, SDI2 is a PPS remappable input and output).
RD2/AND2	RD2	TTL/ST	CMOS/OD	General purpose I/O.
	AND2	AN	—	ADC Channel D0 input.
RD3/AND3	RD3	TTL/ST	CMOS/OD	General purpose I/O.
	AND3	AN	—	ADC Channel D0 input.
RD4/AND4	RD4	TTL/ST	CMOS/OD	General purpose I/O.
	AND4	AN	—	ADC Channel D0 input.
RD5/AND5	RD5	TTL/ST	CMOS/OD	General purpose I/O.
	AND5	AN	—	ADC Channel D0 input.
RD6/AND6	RD6	TTL/ST	CMOS/OD	General purpose I/O.
	AND6	AN	—	ADC Channel D0 input.
RD7/AND7	RD7	TTL/ST	CMOS/OD	General purpose I/O.
	AND7	AN	—	ADC Channel D0 input.
RE0/ANE0	RE0	TTL/ST	CMOS/OD	General purpose I/O.
	ANE0	AN	—	ADC Channel D0 input.
RE1/ANE1	RE1	TTL/ST	CMOS/OD	General purpose I/O.
	ANE1	AN	—	ADC Channel D0 input.
RE2/ANE2	RE2	TTL/ST	CMOS/OD	General purpose I/O.
	ANE2	AN	—	ADC Channel D0 input.
RE3/$\overline{\text{MCLR}}$/IOCE3	RE3	TTL/ST	—	General purpose input only (when $\overline{\text{MCLR}}$ is disabled by the Configuration bit).
	$\overline{\text{MCLR}}$	ST	—	Master clear input with internal weak pull-up resistor.
	IOCE3	TTL/ST	—	Interrupt-on-change input.
RF0/ANF0	RF0	TTL/ST	CMOS/OD	General purpose I/O.
	ANF0	AN	—	ADC Channel D0 input.
RF1/ANF1	RF1	TTL/ST	CMOS/OD	General purpose I/O.
	ANF1	AN	—	ADC Channel D0 input.
RF2/ANF2	RF2	TTL/ST	CMOS/OD	General purpose I/O.
	ANF2	AN	—	ADC Channel D0 input.
RF3/ANF3	RF3	TTL/ST	CMOS/OD	General purpose I/O.
	ANF3	AN	—	ADC Channel D0 input.
RF4/ANF4	RF4	TTL/ST	CMOS/OD	General purpose I/O.
	ANF4	AN	—	ADC Channel D0 input.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C
HV = High Voltage; XTAL = Crystal levels

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to Table 15-4 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 15-5, Table 15-6 and Table 15-7.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMBus input buffer thresholds.

TABLE 18-1: SUMMARY OF REGISTERS ASSOCIATED WITH FIXED VOLTAGE REFERENCE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		264
ADCON0	CHS<5:0>						GO/$\overline{\text{DONE}}$	ADON	277
ADCON1	ADFM	ADCS<2:0>			—	—	ADPREF<1:0>		279
DAC1CON0	DAC1EN	—	DAC1OE1	DAC1OE2	DAC1PSS<1:0>		—	DAC1NSS	287

Legend: – = unimplemented locations read as '0'. Shaded cells are not used with the Fixed Voltage Reference.

20.2 ADC Operation

20.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/$\overline{\text{DONE}}$ bit of the ADCON0 register to a '1' will start the Analog-to-Digital conversion.

Note:	The GO/$\overline{\text{DONE}}$ bit will not be set in the same instruction that turns on the ADC. Refer to **Section 20.2.6 "ADC Conversion Procedure"**.

20.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/$\overline{\text{DONE}}$ bit
- Set the ADIF Interrupt Flag bit
- Update the ADRESH and ADRESL registers with new conversion result

20.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/$\overline{\text{DONE}}$ bit can be cleared in software. The ADRESH and ADRESL registers will be updated with the partially complete Analog-to-Digital conversion sample. Incomplete bits will match the last bit converted.

Note:	A device Reset forces all registers to their Reset state. Thus, the ADC module is turned off and any pending conversion is terminated.

20.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the ADCRC option. When the ADCRC oscillator source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than ADCRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

20.2.5 AUTO-CONVERSION TRIGGER

The Auto-conversion Trigger allows periodic ADC measurements without software intervention. When a rising edge of the selected source occurs, the GO/$\overline{\text{DONE}}$ bit is set by hardware.

The Auto-conversion Trigger source is selected with the ADACT<3:0> bits of the ADACT register.

Using the Auto-conversion Trigger does not assure proper ADC timing. It is the user's responsibility to ensure that the ADC timing requirements are met.

See Table 20-2 for auto-conversion sources.

TABLE 20-2: ADC AUTO-CONVERSION TABLE

ADACT VALUE	SOURCE/ PERIPHERAL	DESCRIPTION
0x00	Disabled	External Trigger Disabled
0x01	ADACTPPS	Pin Selected by ADACTPPS
0x02	TMR0	Timer0 overflow condition
0x03	TMR1	Timer1 overflow condition
0x04	TMR2	Match between Timer2 postscaled value and PR2
0x05	CCP1	CCP1 output
0x06	CCP2	CCP2 output
0x07	PWM3	PWM3 output
0x08	PWM4	PWM4 output
0x09	PWM5	PWM5 output
0x0A	PWM6	PWM6 output
0x0B	NCO1	NCO1 output
0x0C	C1OUT	Comparator C1 output
0x0D	C2OUT	Comparator C2 output
0x0E	IOCIF	Interrupt-on change flag trigger
0x0F	CLC1	CLC1 output
0x10	CLC2	CLC2 output
0x11	CLC3	CLC3 output
0x12	CLC4	CLC4 output
0x13-0xFF	Reserved	Reserved, do not use

20.4 Register Definitions: ADC Control

REGISTER 20-1: ADCON0: ADC CONTROL REGISTER 0

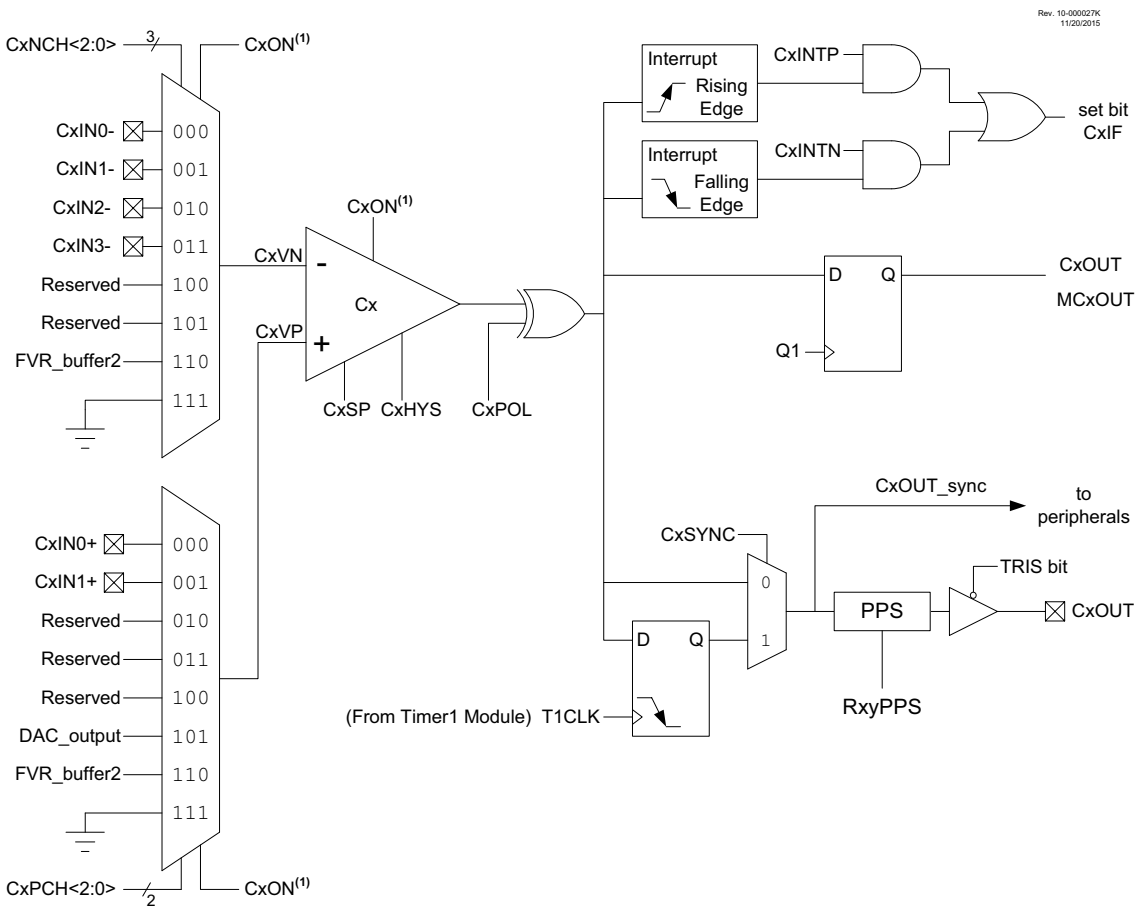
R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
CHS<5:0>						GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-2 **CHS<5:0>:** Analog Channel Select bits
111111 = FVR Buffer 2 reference voltage(2)
111110 = FVR 1Buffer 1 reference voltage(2)
111101 = DAC1 output voltage(1)
111100 = Temperature sensor output(3)
111011 = AVSS (Analog Ground)
111010-100000 = Reserved. No channel connected
101111 = RF7
101110 = RF6
101101 = RF5
101100 = RF4
101011 = RF3
101010 = RF2
101001 = RF1
101000 = RF0
100010 = RE2
100001 = RE1
100000 = RE0
011111 = RD7
011110 = RD6
011101 = RD5
011100 = RD4
011011 = RD3
011010 = RD2
011001 = RD1
011000 = RD0
010111 = RC7(4)
010110 = RC6(4)
010101 = RC5
010100 = RC4
010011 = RC3
010010 = RC2
010001 = RC1
010000 = RC0
001111 = RB7(4)
001110 = RB6(4)
001101 = RB5(4)
001100 = RB4(4)
001011-000110 = Reserved
000101 = RA5
000100 = RA4
000011 = RA3
000010 = RA2
000001 = RA1
000000 = RA0

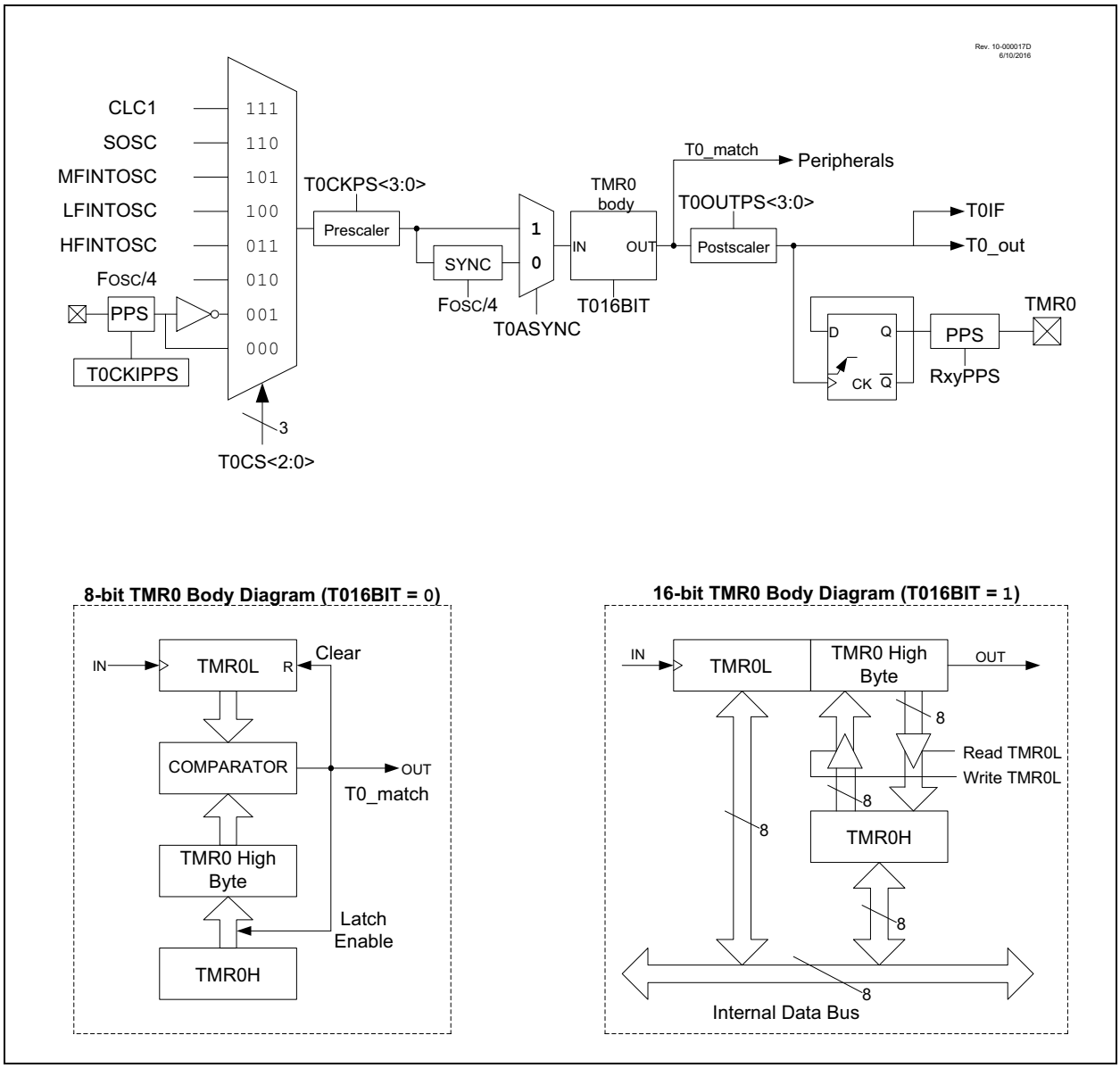
bit 1 **GO/$\overline{\text{DONE}}$:** ADC Conversion Status bit
1 = ADC conversion cycle in progress. Setting this bit starts an ADC conversion cycle.
This bit is automatically cleared by hardware when the ADC conversion has completed.
0 = ADC conversion completed/not in progress

FIGURE 23-2: COMPARATOR MODULE SIMPLIFIED BLOCK DIAGRAM



Note 1: When CxON = 0, all multiplexer inputs are disconnected and the Comparator will produce a '0' at the output.

FIGURE 25-1: BLOCK DIAGRAM OF TIMER0



30.5 Dead-Band Control

The dead-band control provides non-overlapping PWM signals to prevent shoot-through current in PWM switches. Dead-band operation is employed for Half-Bridge and Full-Bridge modes. The CWG contains two 6-bit dead-band counters. One is used for the rising edge of the input source control in Half-Bridge mode or for reverse dead-band Full-Bridge mode. The other is used for the falling edge of the input source control in Half-Bridge mode or for forward dead band in Full-Bridge mode.

Dead band is timed by counting CWG clock periods from zero up to the value in the rising or falling dead-band counter registers. See CWG1DBR and CWG1DBF registers, respectively.

30.5.1 DEAD-BAND FUNCTIONALITY IN HALF-BRIDGE MODE

In Half-Bridge mode, the dead-band counters dictate the delay between the falling edge of the normal output and the rising edge of the inverted output. This can be seen in Figure 30-9.

30.5.2 DEAD-BAND FUNCTIONALITY IN FULL-BRIDGE MODE

In Full-Bridge mode, the dead-band counters are used when undergoing a direction change. The MODE<0> bit of the CWG1CON0 register can be set or cleared while the CWG is running, allowing for changes from Forward to Reverse mode. The CWG1A and CWG1C signals will change upon the first rising input edge following a direction change, but the modulated signals (CWG1B or CWG1D, depending on the direction of the change) will experience a delay dictated by the dead-band counters. This is demonstrated in Figure 30-3.

30.6 Rising Edge and Reverse Dead Band

CWG1DBR controls the rising edge dead-band time at the leading edge of CWG1A (Half-Bridge mode) or the leading edge of CWG1B (Full-Bridge mode). The CWG1DBR value is double-buffered. When EN = 0, the CWG1DBR register is loaded immediately when CWG1DBR is written. When EN = 1, then software must set the LD bit of the CWG1CON0 register, and the buffer will be loaded at the next falling edge of the CWG input signal. If the input source signal is not present for enough time for the count to be completed, no output will be seen on the respective output.

30.7 Falling Edge and Forward Dead Band

CWG1DBF controls the dead-band time at the leading edge of CWG1B (Half-Bridge mode) or the leading edge of CWG1D (Full-Bridge mode). The CWG1DBF value is double-buffered. When EN = 0, the CWG1DBF register is loaded immediately when CWG1DBF is written. When EN = 1 then software must set the LD bit of the CWG1CON0 register, and the buffer will be loaded at the next falling edge of the CWG input signal. If the input source signal is not present for enough time for the count to be completed, no output will be seen on the respective output.

Refer to Figure 30-6 and Figure 30-7 for examples.

TABLE 30-3: SUMMARY OF REGISTERS ASSOCIATED WITH CWG

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CWG1CLKCON	—	—	—	—	—	—	—	CS	401
CWG1ISM	—	—	—	—	IS<3:0>				401
CWG1DBR	—	—	DBR<5:0>						397
CWG1DBF	—	—	DBF<5:0>						397
CWG1CON0	EN	LD	—	—	—	MODE<2:0>			400
CWG1CON1	—	—	IN	—	POLD	POLC	POLB	POLA	396
CWG1AS0	SHUTDOWN	REN	LSBD<1:0>		LSAC<1:0>		—	—	398
CWG1AS1	—	—	—	AS4E	AS3E	AS2E	AS1E	AS0E	399
CWG1STR	OVRD	OVRC	OVRB	OVRA	STRD	STRC	STRB	STRA	400

Legend: – = unimplemented locations read as '0'. Shaded cells are not used by CWG.

The I^2C interface supports the following modes and features:

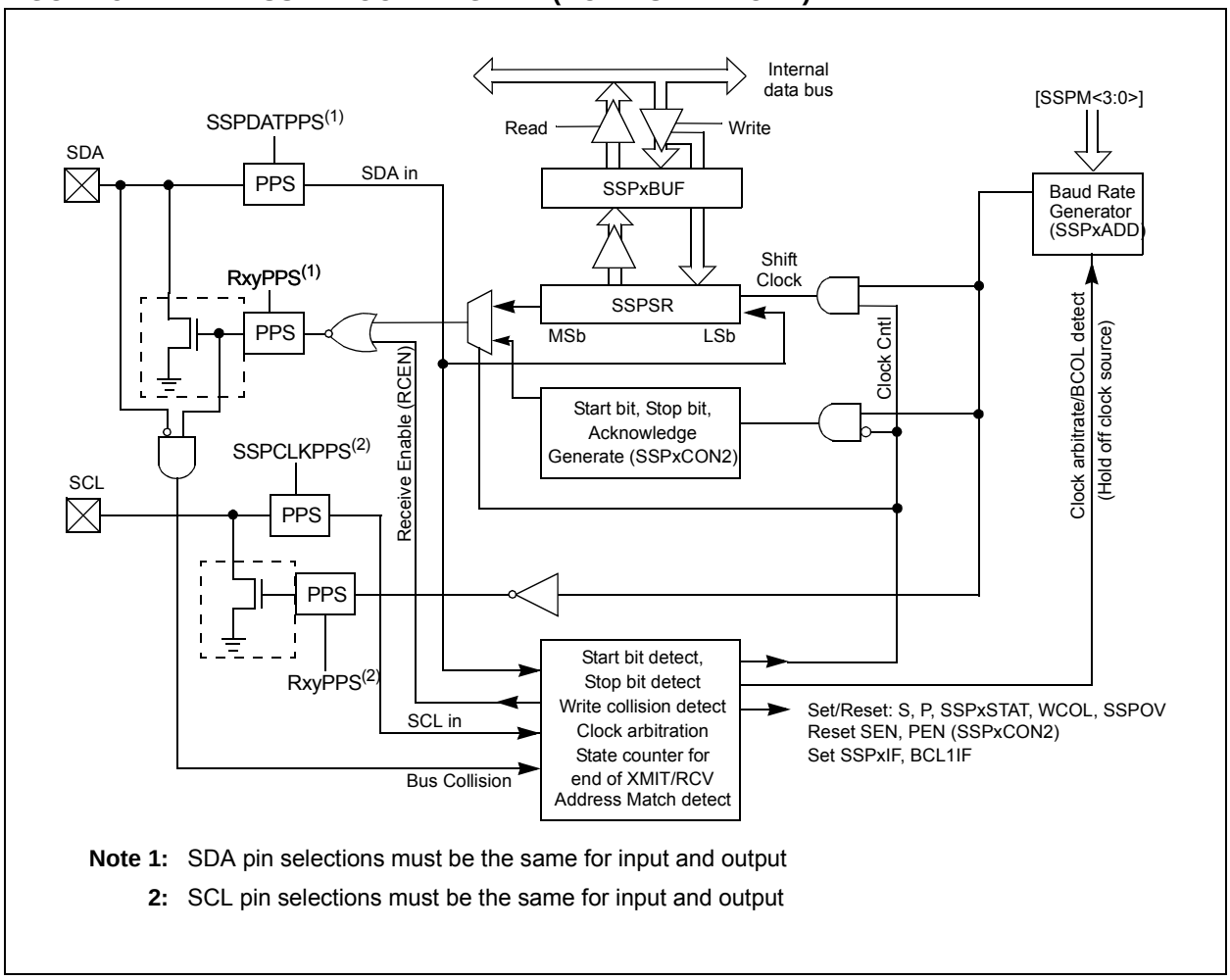
- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- Limited multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking
- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- Selectable SDA hold times

Figure 32-2 is a block diagram of the I^2C interface module in Master mode. Figure 32-3 is a diagram of the I^2C interface module in Slave mode.

Note 1: In devices with more than one MSSP module, it is very important to pay close attention to SSPxCONx register names. SSPxCON1 and SSPxCON2 registers control different operational aspects of the same module, while SSP1CON1 and SSP2CON1 control the same features for two different modules.

2: Throughout this section, generic references to an MSSPx module in any of its operating modes may be interpreted as being equally applicable to MSSP1 or MSSP2. Register names, module I/O signals, and bit names may use the generic designator 'x' to indicate the use of a numeral to distinguish a particular module when required.

FIGURE 32-2: MSSP BLOCK DIAGRAM (I^2C MASTER MODE)



Note 1: SDA pin selections must be the same for input and output

2: SCL pin selections must be the same for input and output

32.2.3 SPI MASTER MODE

The master can initiate the data transfer at any time because it controls the SCK line. The master determines when the slave (Processor 2, Figure 32-5) is to broadcast data by the software protocol.

In Master mode, the data is transmitted/received as soon as the SSPxBUF register is written to. If the SPI is only going to receive, the SDO output could be disabled (programmed as an input). The SSPxSR register will continue to shift in the signal present on the SDI pin at the programmed clock rate. As each byte is received, it will be loaded into the SSPxBUF register as if a normal received byte (interrupts and Status bits appropriately set).

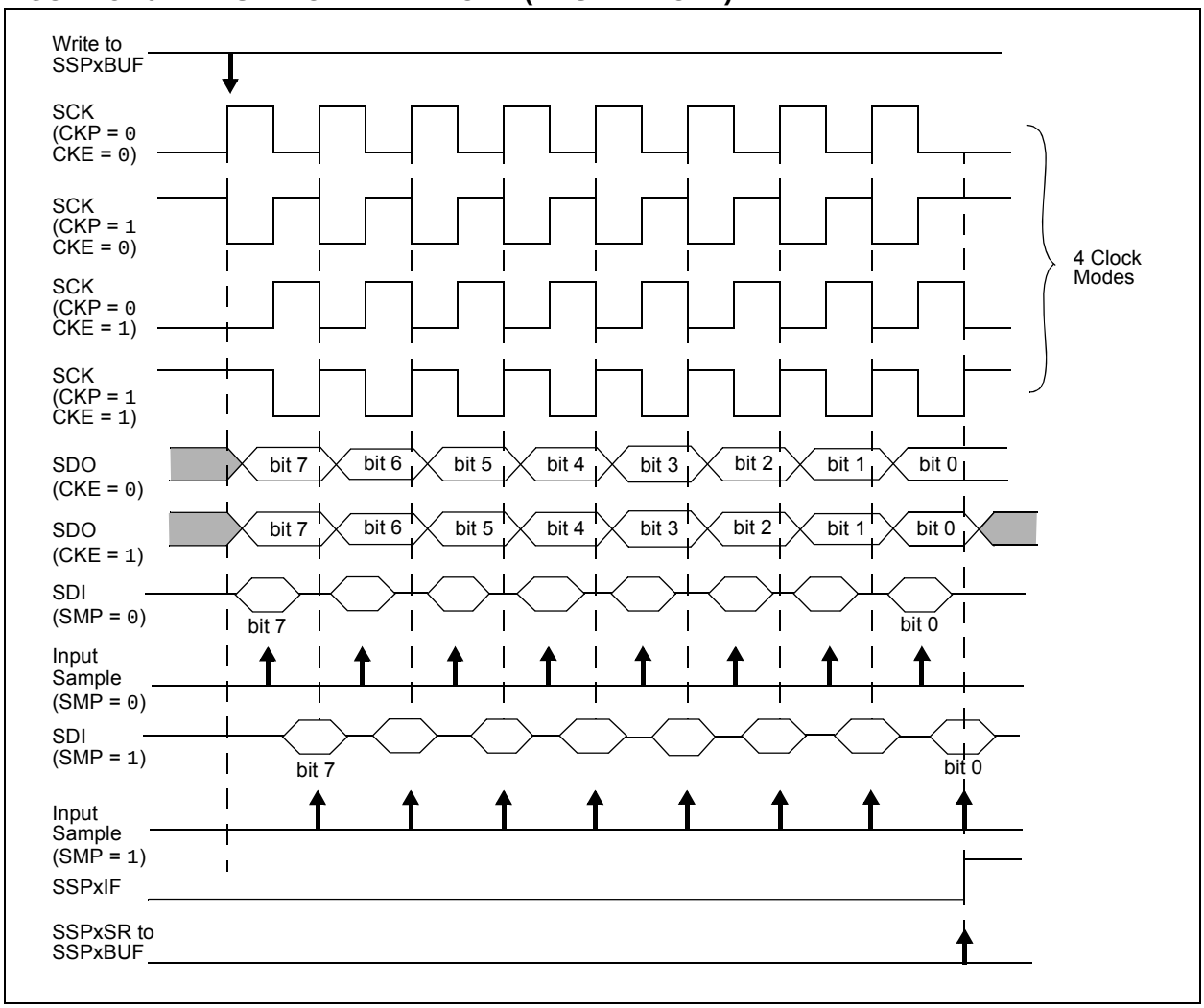
The clock polarity is selected by appropriately programming the CKP bit of the SSPxCON1 register and the CKE bit of the SSPxSTAT register. This then, would give waveforms for SPI communication as shown in Figure 32-6, Figure 32-8, Figure 32-9 and Figure 32-10, where the MSB is transmitted first. In Master mode, the SPI clock rate (bit rate) is user programmable to be one of the following:

- FOSC/4 (or TCY)
- FOSC/16 (or 4 * TCY)
- FOSC/64 (or 16 * TCY)
- Timer2 output/2
- FOSC/(4 * (SSPxADD + 1))

Figure 32-6 shows the waveforms for Master mode.

When the CKE bit is set, the SDO data is valid before there is a clock edge on SCK. The change of the input sample is shown based on the state of the SMP bit. The time when the SSPxBUF is loaded with the received data is shown.

FIGURE 32-6: SPI MODE WAVEFORM (MASTER MODE)



32.6.4 I²C MASTER MODE START CONDITION TIMING

To initiate a Start condition (Figure 32-26), the user sets the Start Enable bit, SEN bit of the SSPxCON2 register. If the SDA and SCL pins are sampled high, the Baud Rate Generator is reloaded with the contents of SSPxADD<7:0> and starts its count. If SCL and SDA are both sampled high when the Baud Rate Generator times out (TBRG), the SDA pin is driven low. The action of the SDA being driven low while SCL is high is the Start condition and causes the S bit of the SSPxSTAT1 register to be set. Following this, the Baud Rate Generator is reloaded with the contents of SSPxADD<7:0> and resumes its count. When the Baud Rate Generator times out (TBRG), the SEN bit of the SSPxCON2 register will be automatically cleared by hardware; the Baud Rate Generator is suspended, leaving the SDA line held low and the Start condition is complete.

Note 1: If at the beginning of the Start condition, the SDA and SCL pins are already sampled low, or if during the Start condition, the SCL line is sampled low before the SDA line is driven low, a bus collision occurs, the Bus Collision Interrupt Flag, BCLIF, is set, the Start condition is aborted and the I²C module is reset into its Idle state.

2: The Philips I²C specification states that a bus collision cannot occur on a Start.

FIGURE 32-26: FIRST START BIT TIMING

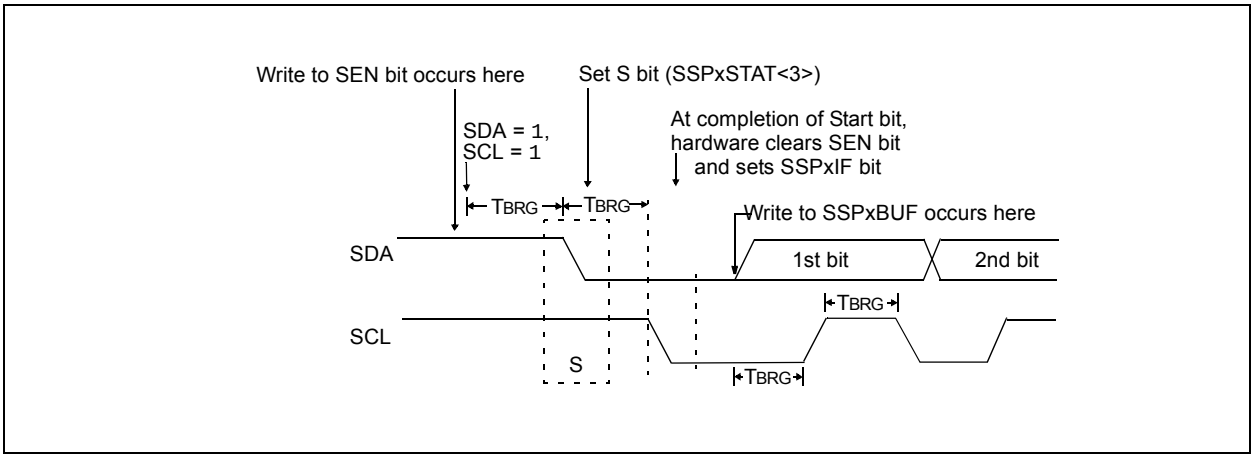


FIGURE 34-1: CLOCK REFERENCE BLOCK DIAGRAM

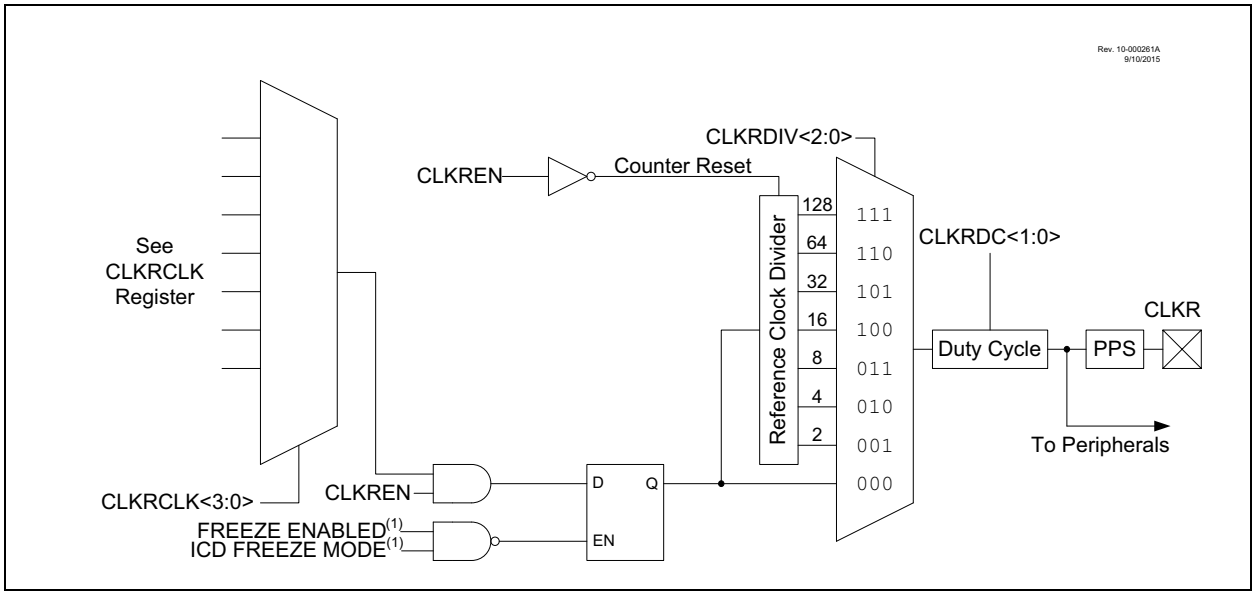
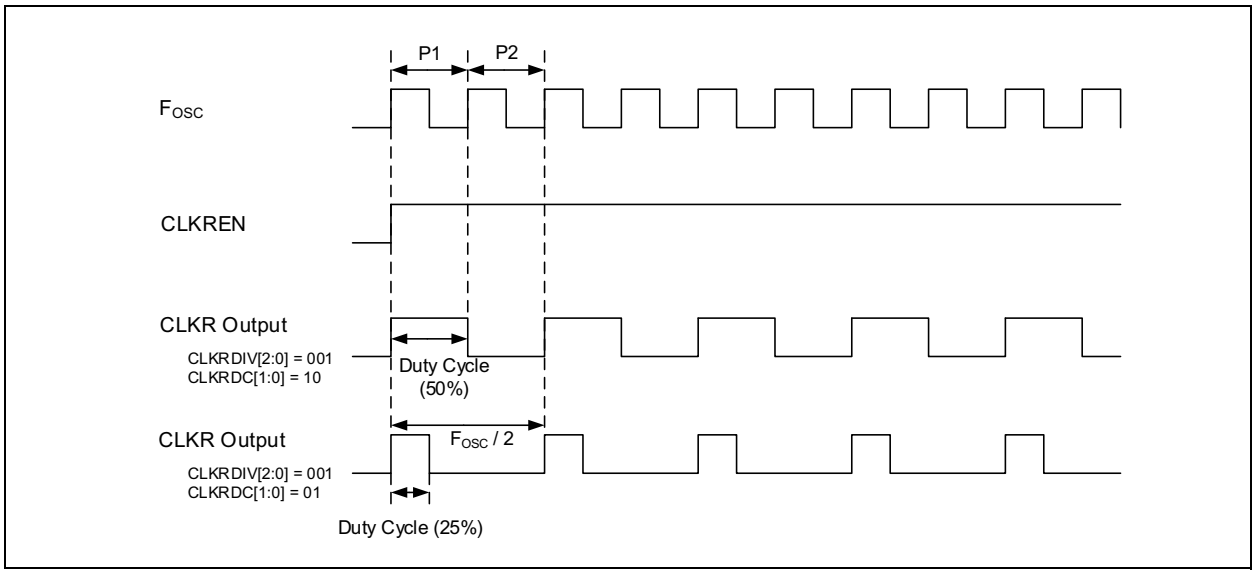


FIGURE 34-2: CLOCK REFERENCE TIMING



REGISTER 34-1: CLKRCON: REFERENCE CLOCK CONTROL REGISTER

R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
CLKREN	—	—	CLKRDC<1:0>		CLKRDIV<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CLKREN:** Reference Clock Module Enable bit
- 1 = Reference clock module enabled
- 0 = Reference clock module is disabled

bit 6-5 **Unimplemented:** Read as '0'

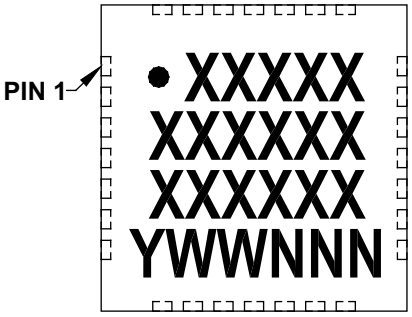
bit 4-3 **CLKRDC<1:0>:** Reference Clock Duty Cycle bits (1)
- 11 = Clock outputs duty cycle of 75%
- 10 = Clock outputs duty cycle of 50%
- 01 = Clock outputs duty cycle of 25%
- 00 = Clock outputs duty cycle of 0%

bit 2-0 **CLKRDIV<2:0>:** Reference Clock Divider bits
- 111 = Base clock value divided by 128
- 110 = Base clock value divided by 64
- 101 = Base clock value divided by 32
- 100 = Base clock value divided by 16
- 011 = Base clock value divided by 8
- 010 = Base clock value divided by 4
- 001 = Base clock value divided by 2
- 000 = Base clock value

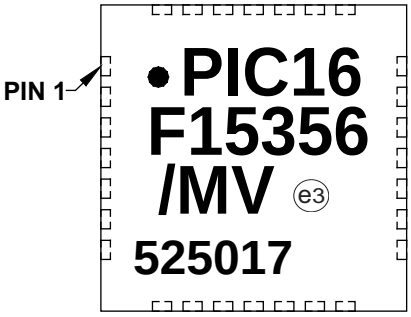
Note 1: Bits are valid for reference clock divider values of two or larger, the base clock cannot be further divided.

40.1 Package Marking Information (Continued)

28-Lead UQFN (4x4x0.5 mm) and (6x6 mm)



Example



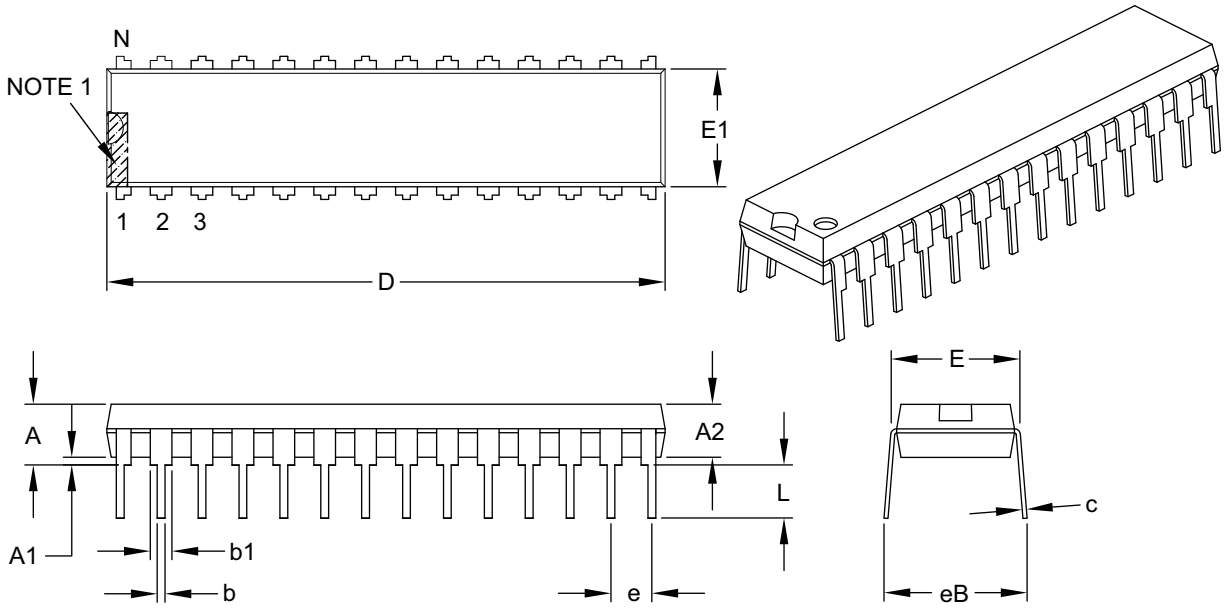
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
		Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

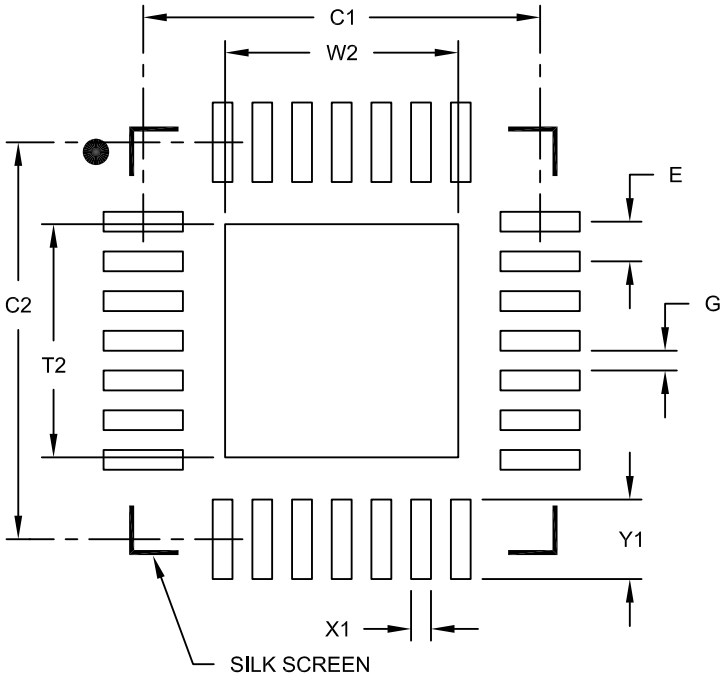
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 4x4 mm Body [UQFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			2.35
Optional Center Pad Length	T2			2.35
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2152A